

74HC42

BCD to decimal decoder (1-of-10)

Rev. 3 — 27 September 2016

Product data sheet

1. General description

The 74HC42 is a one of ten BCD to decimal decoder. It accepts four BCD inputs (0A to 3A) and provides ten mutually exclusive outputs (0Y to 9Y). The logic design ensures that all outputs are HIGH when binary codes greater than nine are applied to the inputs. The most significant input (3A) produces an useful inhibit function when the device is used as a 1-of-8 decoder. The 3A input can also be used as the data input in an 8-output demultiplexer application. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of V_{CC} .

2. Features and benefits

- Complies with JEDEC standard no. 7A
- Input levels:
 - ◆ For 74HC42: CMOS level
- Mutually exclusive outputs
- 1-of-8 demultiplexing capability
- Outputs disabled for input codes above nine
- ESD protection:
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V
- Specified from $-40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$ and $-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$

3. Ordering information

Table 1. Ordering information

Type number	Temperature range	Name	Description	Version
74HC42D	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



4. Functional diagram

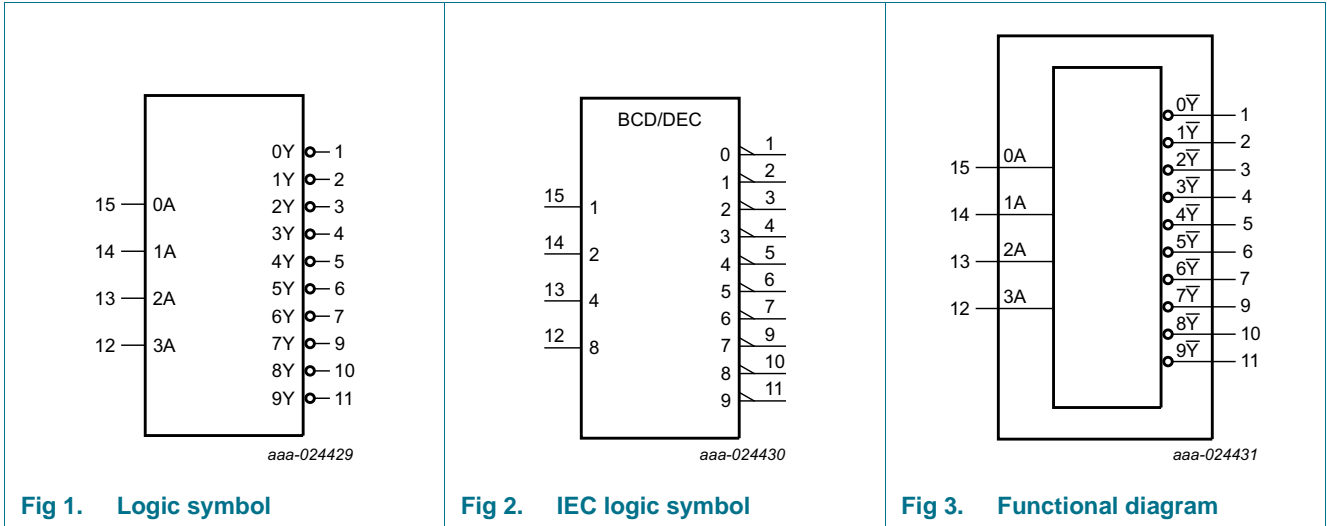


Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Functional diagram

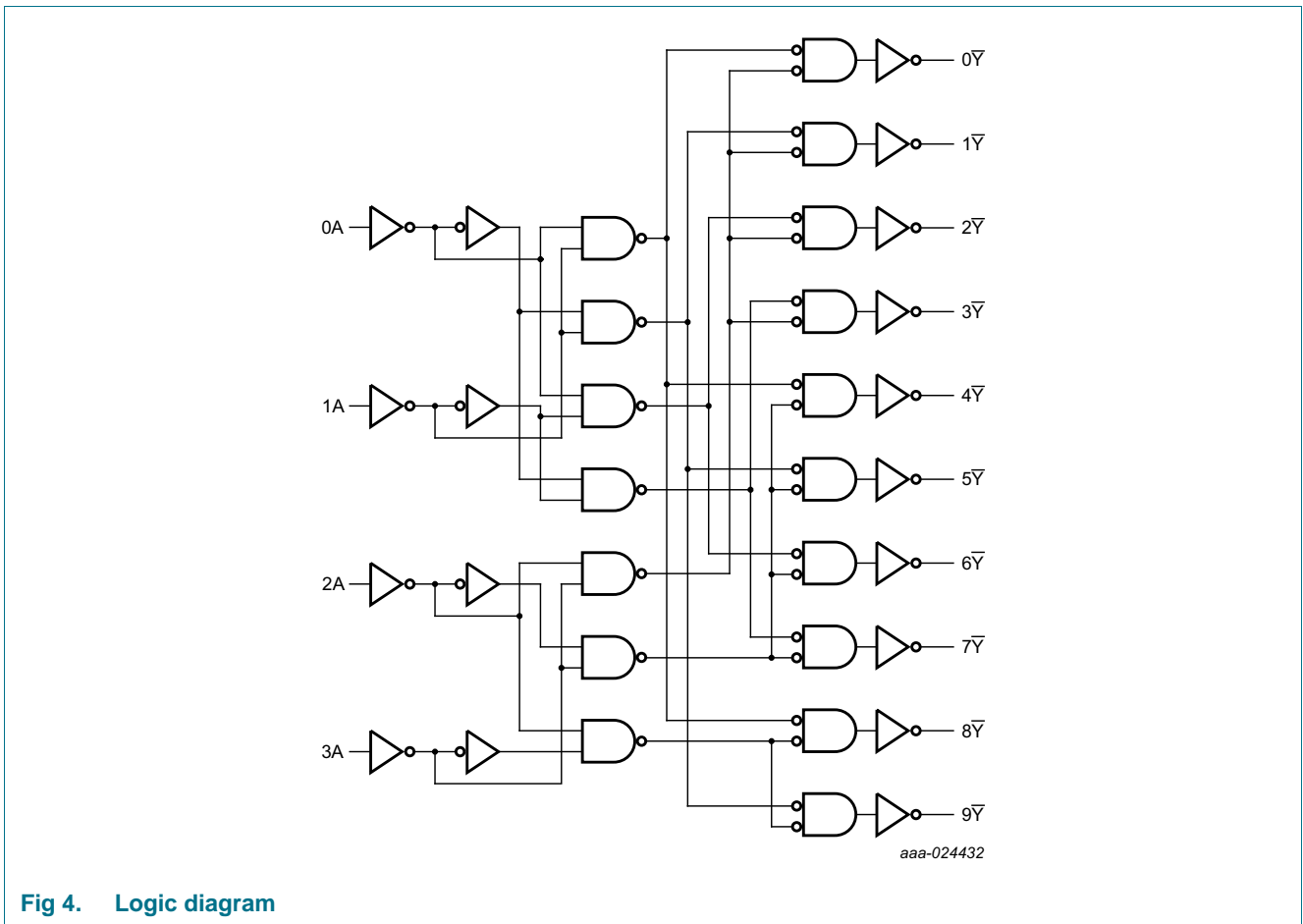


Fig 4. Logic diagram

5. Pinning information

5.1 Pinning

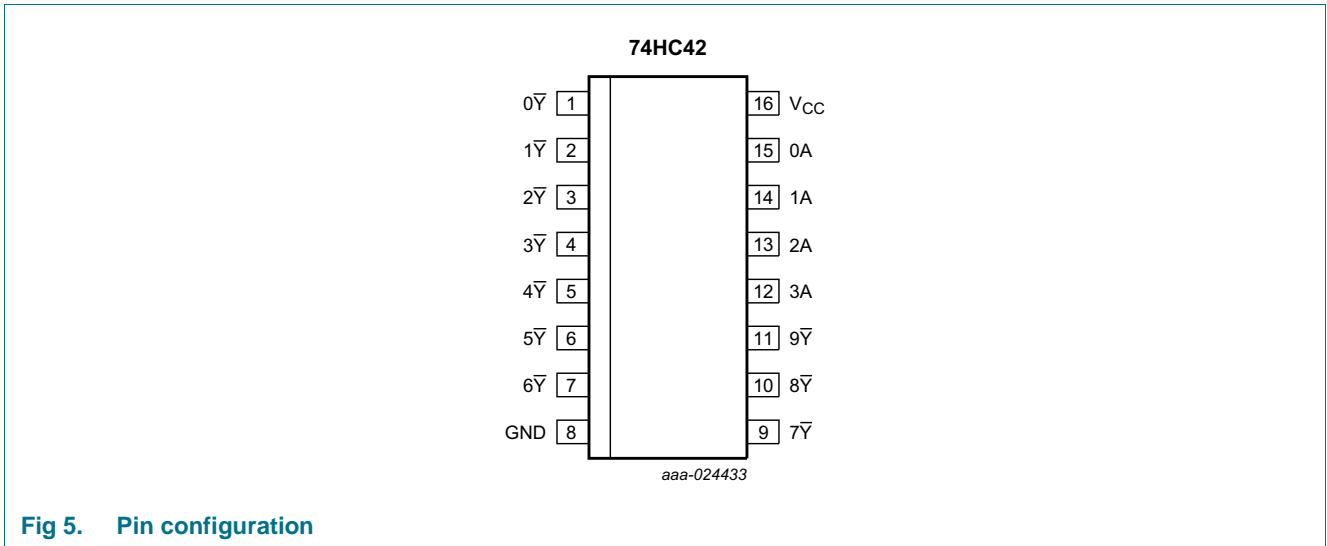


Fig 5. Pin configuration

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
0Y-bar, 1Y-bar, 2Y-bar, 3Y-bar, 4Y-bar, 5Y-bar, 6Y-bar, 7Y-bar, 8Y-bar, 9Y-bar	1, 2, 3, 4, 5, 6, 7, 9, 10, 11	multiplexer output
GND	8	ground (0 V)
0A, 1A, 2A, 3A	15, 14, 13, 12	data input
V _{CC}	16	supply voltage

6. Functional description

Table 3. Function table^[1]

Inputs				Outputs										
3A	2A	1A	0A	0 \bar{Y}	1 \bar{Y}	2 \bar{Y}	3 \bar{Y}	4 \bar{Y}	5 \bar{Y}	6 \bar{Y}	7 \bar{Y}	8 \bar{Y}	9 \bar{Y}	
L	L	L	L	L	H	H	H	H	H	H	H	H	H	H
L	L	L	H	H	L	H	H	H	H	H	H	H	H	H
L	L	H	L	H	H	L	H	H	H	H	H	H	H	H
L	L	H	H	H	H	H	L	H	H	H	H	H	H	H
L	H	L	L	H	H	H	H	L	H	H	H	H	H	H
L	H	L	H	H	H	H	H	H	L	H	H	H	H	H
L	H	H	L	H	H	H	H	H	H	L	H	H	H	H
L	H	H	H	H	H	H	H	H	H	H	L	H	H	H
H	L	L	L	H	H	H	H	H	H	H	H	L	H	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L	H
H	L	H	L	H	H	H	H	H	H	H	H	H	H	H
H	L	H	H	H	H	H	H	H	H	H	H	H	H	H
H	H	L	L	H	H	H	H	H	H	H	H	H	H	H
H	H	L	H	H	H	H	H	H	H	H	H	H	H	H
H	H	H	L	H	H	H	H	H	H	H	H	H	H	H
H	H	H	H	H	H	H	H	H	H	H	H	H	H	H

- [1] H = HIGH voltage level;
L = LOW voltage level

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$ ^[1]	-	± 20	mA
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$ ^[1]	-	± 20	mA
I_O	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	± 25	mA
I_{CC}	supply current		-	50	mA
I_{GND}	ground current		-50	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation		-	500	mW ^[2]

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
[2] For SO16 package: P_{tot} derates linearly with 8 mW/K above 70 °C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC42			Unit
			Min	Typ	Max	
V _{CC}	supply voltage		2.0	5.0	6.0	V
V _I	input voltage		0	-	V _{CC}	V
V _O	output voltage		0	-	V _{CC}	V
T _{amb}	ambient temperature		-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V _{CC} = 2.0 V	-	-	625	ns/V
		V _{CC} = 4.5 V	-	1.67	139	ns/V
		V _{CC} = 6.0 V	-	-	83	ns/V

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{IH}	HIGH-level input voltage	V _{CC} = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V _{CC} = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V _{CC} = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V _{IL}	LOW-level input voltage	V _{CC} = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V _{CC} = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V _{CC} = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V _{OH}	HIGH-level output voltage	V _I = V _{IH} or V _{IL}								
		I _O = -20 μA; V _{CC} = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I _O = -20 μA; V _{CC} = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = -20 μA; V _{CC} = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I _O = -4.0 mA; V _{CC} = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
V _{OL}	LOW-level output voltage	I _O = -5.2 mA; V _{CC} = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
		V _I = V _{IH} or V _{IL}								
		I _O = 20 μA; V _{CC} = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I _O = 20 μA; V _{CC} = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
I _I	input leakage current	I _O = 4.0 mA; V _{CC} = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I _O = 5.2 mA; V _{CC} = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
		V _I = V _{CC} or GND; V _{CC} = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 6.0 V	-	-	8.0	-	80	-	160	μA
C _I	input capacitance		-	3.5	-	-	-	-	-	pF

10. Dynamic characteristics

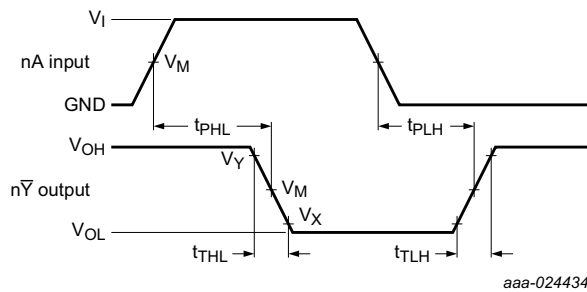
Table 7. Dynamic characteristics

Voltages are referenced to GND (ground = 0 V); $C_L = 50 \text{ pF}$ unless otherwise specified; for test circuit see [Figure 7](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t_{pd}	propagation delay	nA to \overline{nY} ; see Figure 6 [1]								
		$V_{CC} = 2.0 \text{ V}$	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5 \text{ V}$	-	17	30	-	38	-	45	ns
		$V_{CC} = 5.0 \text{ V}; C_L = 15 \text{ pF}$	-	17	-	-	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	-	14	26	-	33	-	38	ns
t_t	transition time	see Figure 6 [2]								
		$V_{CC} = 2.0 \text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5 \text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0 \text{ V}$	-	6	13	-	16	-	19	ns
C_{PD}	power dissipation capacitance	per package; $V_I = \text{GND to } V_{CC}$ [3]	-	37	-	-	-	-	-	pF

- [1] t_{pd} is the same as t_{PHL} and t_{PLH} .
- [2] t_t is the same as t_{THL} and t_{TLH} .
- [3] C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$ where:
 f_i = input frequency in MHz;
 f_o = output frequency in MHz;
 C_L = output load capacitance in pF;
 V_{CC} = supply voltage in V;
 N = number of inputs switching;
 $\sum(C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

11. Waveforms



Measurement points are given in [Table 8](#).

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 6. Input (nA) to output (\overline{nY}) propagation delays and output transition times

Table 8. Measurement points

Input	Output		
V_M	V_M	V_X	V_Y
$0.5V_{CC}$	$0.5V_{CC}$	$0.1V_{CC}$	$0.9V_{CC}$

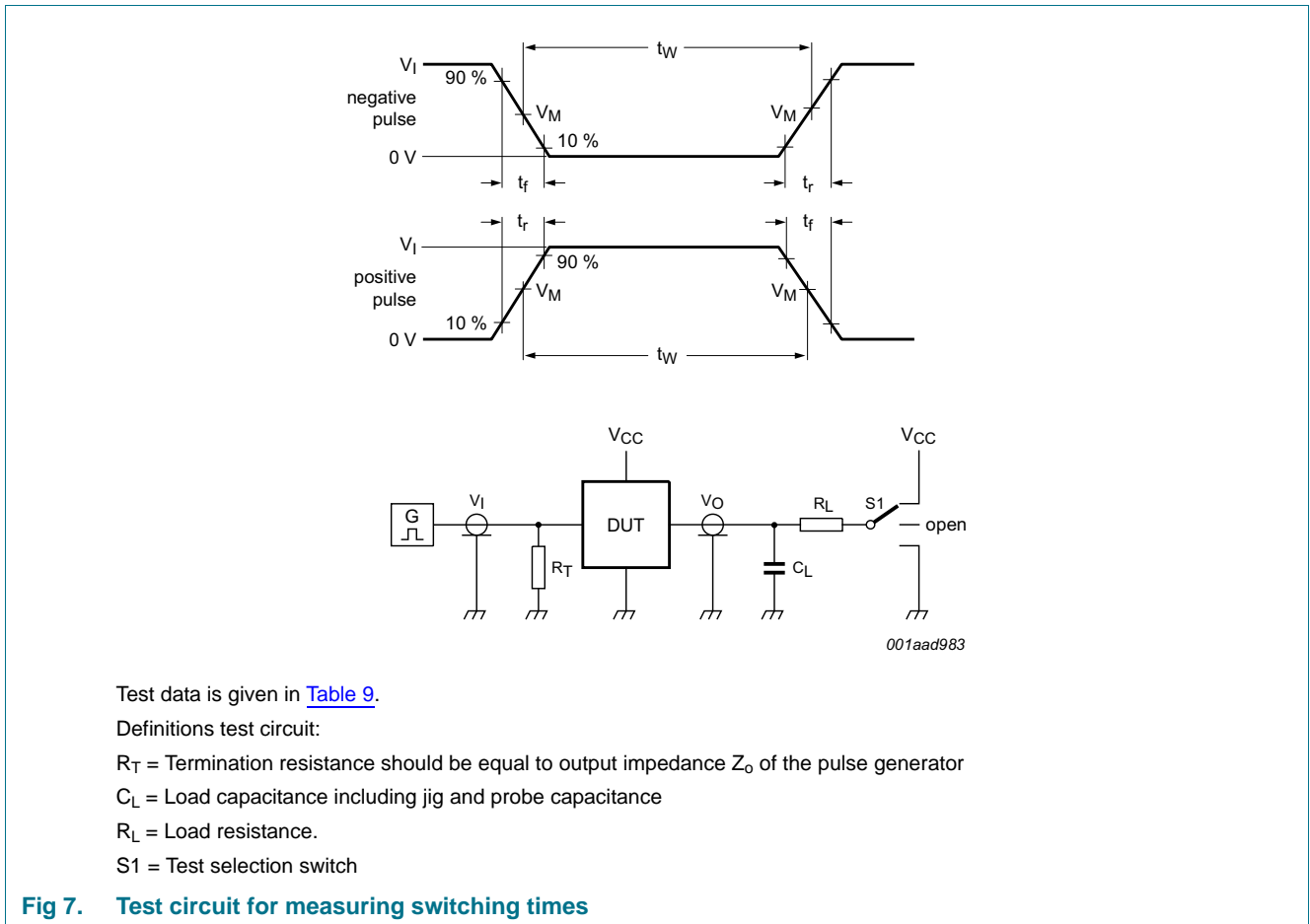


Fig 7. Test circuit for measuring switching times

Table 9. Test data

Type	Input		Load		S1 position
	V_I	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}
74HC42	V_{CC}	6 ns	15 pF, 50 pF	1 k Ω	open

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

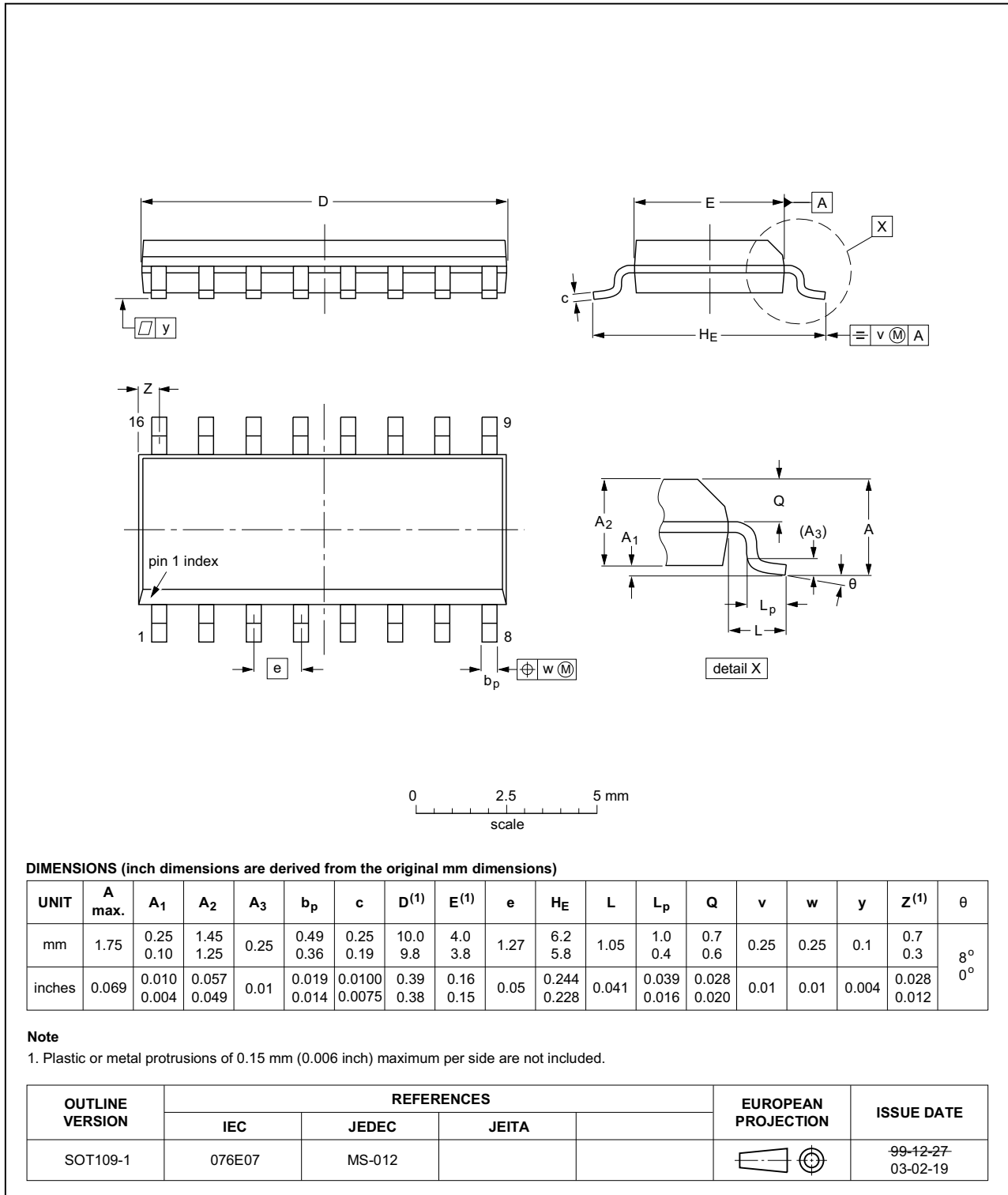


Fig 8. Package outline SOT109-1 (SO16)

13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal-Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC42 v.3	20160927	Product data sheet	-	74HC_HCT42 v.2
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. Legal texts have been adapted to the new company name where appropriate. Type numbers 74HC42N, 74HCT42N and 74HCT42D removed. 			
74HC_HCT42 v.2	19901201	Product specification	-	-

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Document status ^{[1][2]}	Product status ^[3]	Definition
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Product [short] data sheet	Production	This document contains the product specification.

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[2] The term 'short data sheet' is explained in section "Definitions".

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